

A1
would

at least one semiconductor die having an active surface with at least one electrical connection area disposed on said semiconductor die active surface, said at least one semiconductor die oriented having said at least one electrical connection area substantially aligned with said at least one semiconductor substrate opening; and

at least one adhesive tape interposed between and attaching said semiconductor die active surface and said semiconductor substrate first surface, wherein a width of said at least one adhesive tape extends proximate an edge of said at least one semiconductor die to proximate an edge of said at least one semiconductor substrate opening; [and said at least one semiconductor die is oriented such that said at least one electrical connection area is aligned with said at least one semiconductor substrate opening].

2. (Amended) The semiconductor die assembly of claim 1, wherein said width of said at least one adhesive tape extends beyond said edge of said at least one semiconductor substrate opening a distance into said at least one semiconductor substrate opening to provide a detectable surface within said at least one semiconductor substrate opening.

D1

3. (Amended) The semiconductor die assembly of claim 1, wherein said width of said at least one adhesive tape extends beyond said edge of said at least one semiconductor die a distance on said semiconductor substrate first surface to provide a detectable adhesive tape surface on said semiconductor substrate first surface.

Sub B²

A2
could

15. (Amended) A computer comprising:
at least one semiconductor die assembly, said semiconductor die assembly comprising:
a semiconductor substrate having a first surface and a second surface, wherein said semiconductor substrate includes at least one opening defined [through said semiconductor substrate] therethrough between said semiconductor substrate first surface and said semiconductor substrate second surface;
at least one semiconductor die having an active surface with at least one electrical connection area disposed on said semiconductor die active surface, said at least one semiconductor